

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>CHANG SEOB HONG</td> <td>11/29/2013</td> </tr> <tr> <td>EUN JUNG JO</td> <td>11/29/2013</td> </tr> <tr> <td>KYU HWAN OH</td> <td>11/29/2013</td> </tr> <tr> <td>KANG HYUN LEE</td> <td>11/29/2013</td> </tr> </tbody> </table>		Name	Execution Date	CHANG SEOB HONG	11/29/2013	EUN JUNG JO	11/29/2013	KYU HWAN OH	11/29/2013	KANG HYUN LEE	11/29/2013
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<table border="1"> <tr> <td>Name:</td> <td>SAMSUNG ELECTRO-MECHANICS CO., LTD.</td> </tr> <tr> <td>Street Address:</td> <td>314, MAETAN 3-DONG, YEONGTONG-GU, SUWON</td> </tr> <tr> <td>City:</td> <td>GYUNGGI-DO</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> <tr> <td>Postal Code:</td> <td>443-743</td> </tr> </table>		Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.	Street Address:	314, MAETAN 3-DONG, YEONGTONG-GU, SUWON	City:	GYUNGGI-DO	State/Country:	KOREA, REPUBLIC OF	Postal Code:	443-743
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PROPERTY NUMBERS Total: 1											
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Application Number:	14142719										
CORRESPONDENCE DATA											
<p>Fax Number: (323)934-0202</p> <p>Phone: 323-934-2300</p> <p>Email: LA_Mail@la.ladas.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: LADAS & PARRY</p> <p>Address Line 1: 5670 WILSHIRE BOULEVARD, SUITE 2100</p> <p>Address Line 4: LOS ANGELES, CALIFORNIA 90036-5679</p>											
ATTORNEY DOCKET NUMBER:	B-8194 629123-5										
NAME OF SUBMITTER:	DIANA J. PISANI										
Signature:	/Diana J. Pisani 71664/										

Date:

01/06/2014

Total Attachments: 4

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PATENT

REEL: 031892 FRAME: 0984

Attorney's Docket No.

B-8194 629123-5

Patent

For: ☒ U.S. and/or ☐ Foreign Rights
For: ☒ U.S. Application or ☐ U.S. Patent
For: ☐ PCT Application
By: ☒ Inventor(s) or ☐ Present Owner

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration,

ASSIGNORS:

(inventor(s) or person(s) or
entity(ies) who own the invention)

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(Address)

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(Nationality)

(Assignment of Invention [16-3]--page 1 of 4)

(4) LEE, Kang Hyun
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c/o Samsung Electro-Mechanics Co., Ltd.,
314, Maetan 3-dong, Yeongtong-gu,
Suwon, Gyunggi-do 443-743, Korea
(Address)

Korea
(Nationality)

hereby confirm that ASSIGNORS sell, assign and transfer to

ASSIGNEE: SAMSUNG ELECTRO-MECHANICS CO., LTD.
(type or print name(s) of ASSIGNEE(S))

314, Maetan 3-dong, Yeongtong-gu,
Suwon, Gyunggi-do 443-743, Korea
(Address)

Korea
(Nationality)

and the successors, assigns and legal representatives of the ASSIGNEE
(complete one of the following)

☒ [X] the entire right, title and interest

☐ [] an undivided _____ percent (_____ %) interest for the

United States and its territorial possessions

(check the following box if foreign rights are also to be assigned)

☐ [] and in all foreign countries, including all rights to claim

priority, in and to any and all improvements which are disclosed in the invention
entitled: EXTERNAL CONNECTION TERMINAL, SEMICONDUCTOR
PACKAGE HAVING EXTERNAL CONNECTION TERMINAL,
AND METHODS FOR MANUFACTURING THE SAME

(check and complete (a), (b), (c) or (d)) and which is found in

(a) ☐ [] U.S. patent application executed on even date herewith

(b) ☐ [] U.S. patent application executed on _____

☒ [X] To comply with 37 CFR 3.21 for recordal of this assignment, I, an
ASSIGNOR signing below, hereby authorize and request my attorney, as named
in the Declaration and Power of Attorney I executed for this invention on the

execution date stated above, to insert below the filing date and application number when it becomes known.

(c) ☒ U.S. Application serial no. 14/142,719 filed on December 27, 2013

(d) ☐ International application no. _____

(e) ☐ U.S. Patent no. _____ issued _____

☐ A change of address to which correspondence is to be sent regarding patent maintenance fees is being sent separately.

(also check (F) if foreign application(s) is also being assigned)

(f) ☐ and any legal equivalent thereof in a foreign country, including the right to claim priority and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNORS hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

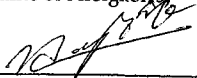
ASSIGNORS further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNORS and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.

IN WITNESS WHEREOF, I/We have hereunto set hand and seal this

29th day of November, 2013 (date of signing).

HONG, Chang Seob

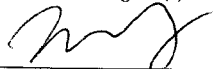
Name of Assignor(s)


Signature of ASSIGNOR(S)

IN WITNESS WHEREOF, I/We have hereunto set hand and seal this
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IO, Eun Jung

Name of Assignor(s)

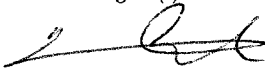


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OH, Kyu Hwan

Name of Assignor(s)



Signature of ASSIGNOR(S)

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LEE, Kang Hyun

Name of Assignor(s)



Signature of ASSIGNOR(S)

(Assignment of Invention [16-3]--page 4 of 4)